

Title (en)

METHOD FOR DIGITAL FORMATION OF 2D MATERIALS STRUCTURES, APPLICATIONS THEREOF AND A SYSTEM

Title (de)

VERFAHREN ZUR DIGITALEN BILDUNG VON 2D-MATERIALSTRUKTUREN, ANWENDUNGEN DAVON UND SYSTEM

Title (fr)

PROCÉDÉ DE FORMATION NUMÉRIQUE DE STRUCTURES DE MATÉRIAUX 2D, SES APPLICATIONS ET SYSTÈME

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2022248893A1] A system and method for performing is laser induced forward transfer (LIFT) of 2D materials is disclosed. The method includes generating a receiver substrate, generating a donor substrate, wherein the donor substrate comprises a back surface and a front surface, applying a coating to the front surface, wherein the coating includes donor material, aligning the front surface of the donor substrate to be parallel to and facing the receiver substrate, wherein the donor material is disposed adjacent to the target layer, and irradiating the coating through the back surface of the donor substrate with one or more laser pulses produced by a laser to transfer a portion of the donor material to the target layer. The donor material may include Bi₂S₃-xS_x, MoS₂, hexagonal boron nitride (h-BN) or graphene. The method may be used to create touch sensors and other electronic components.

IPC 8 full level

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See references of WO 2022248893A1

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